PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHIGEO SAKATA	11/22/2021
TAKAHIRO KAJINISHI	11/22/2021
SEIICHIRO KIHARA	11/22/2021
HIROSHI TAKAHARA	11/22/2021

RECEIVING PARTY DATA

Name:	QUALTEC CO., LTD.
Street Address:	230 SANBOCHO, 4-CHOME
Internal Address:	SAKAI-KU, SAKAI-SHI
City:	OSAKA-FU
State/Country:	JAPAN
Postal Code:	590-0906

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17616673

CORRESPONDENCE DATA

Fax Number: (703)997-4565

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (305) 938-7119 **Email:** mail@j-pat.jp

Correspondent Name: J-PAT U.S. PATENT LEGAL SERVICES

Address Line 1: OOE BUILDING, NO. 508

Address Line 2: 8-1 NISHITEMMA 2-CHOME, KITA-KU

Address Line 4: OSAKA-SHI, JAPAN 530-0047

ATTORNEY DOCKET NUMBER:	035.0003
NAME OF SUBMITTER:	JAMES W. JUDGE
SIGNATURE:	/James Judge/
DATE SIGNED:	12/05/2021
	This document serves as an Oath/Declaration (37 CFR 1.63).

PATENT 507009590 REEL: 058289 FRAME: 0758

Total Attachments: 4

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PATENT REEL: 058289 FRAME: 0759

Whereas **Shigeo Sakata**, hereinafter referred to as the inventor, as being either a sole inventor or one of joint inventors, has invented certain new and useful improvements in

Semiconductor Component Test Device and Method of Testing Semiconductor Components,

for which the inventor has executed an application for United States Patent by his or her signature below, and

WHEREAS **Qualtec Co., Ltd.**, a corporation organized and existing under the laws of Japan, and hereinafter referred to as the assignee, whose mailing address is

230 Sanböchö 4-Chō, Sakai-ku, Sakai-shi, Osaka-fu, 590-0906, Japan,

is desirous of acquiring the entire rights in the patent application named above, and insofar as the same yields any United States patent(s), the title to and interest in the same:

Now, therefore, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the inventor assigns, and transfers, unto the assignee, the entire rights in the patent application, and the title to and interest in the same insofar as the same yields any United States patent(s); and the inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all any such patent(s) to the assignee, as that of the entire title to and interest in any such patent(s), for the sole use and behoof of the assignee and the assignee's legal representatives, as fully and entirely as any such patent(s) would have been held by the inventor had the present assignment not been made.

Statements Required by 35 U.S.C. § 115(b) and (c)

As the above-named inventor, I hereby declare that:

上記発明者である私は、次のことがらを宣誓します。

The above-identified application was made or authorized to be made by me.

上記の出願は私自身、あるいは私が権限を授与したものによって行われたものです。

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

私は本出願書中にあらわれるもともとの発明者、あるいはもともとの共同発明者です。

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

本宣誓書において故意に虚偽の申し立てを行った場合は 18 U.S.C. 1001 により、罰金あるいは最高五(5)年の禁固刑、あるいはその両方による罰則の対象となることを認めます。

Legal Name 発明者の正		Shigeo Sakata	Date 日付	2021/11/22
Signature 署名	吸	闽		

^{*} Declaration for patent application using an Application Data Sheet.

WHEREAS **Takahiro Kajinishi**, hereinafter referred to as the inventor, as being either a sole inventor or one of joint inventors, has invented certain new and useful improvements in

Semiconductor Component Test Device and Method of Testing Semiconductor Components,

for which the inventor has executed an application for United States Patent by his or her signature below, and

WHEREAS **Qualtec Co., Ltd.**, a corporation organized and existing under the laws of Japan, and hereinafter referred to as the assignee, whose mailing address is

230 Sanbōchō 4-Chō, Sakai-ku, Sakai-shi, Osaka-fu, 590-0906, Japan,

is desirous of acquiring the entire rights in the patent application named above, and insofar as the same yields any United States patent(s), the title to and interest in the same:

Now, therefore, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the inventor assigns, and transfers, unto the assignee, the entire rights in the patent application, and the title to and interest in the same insofar as the same yields any United States patent(s); and the inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all any such patent(s) to the assignee, as that of the entire title to and interest in any such patent(s), for the sole use and behoof of the assignee and the assignee's legal representatives, as fully and entirely as any such patent(s) would have been held by the inventor had the present assignment not been made.

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As the above-named inventor, I hereby declare that:

上記発明者である私は、次のことがらを宣誓します。

The above-identified application was made or authorized to be made by me.

上記の出願は私自身、あるいは私が権限を授与したものによって行われたものです。

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Legal Name 発明者の正		Takahiro Kajinishi	Date 日付	2021年11月22日
Signature 署名	税	面孝博		

^{*} Declaration for patent application using an Application Data Sheet.

j-pat Ref.	035.0003
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WHEREAS **Seiichiro Kihara**, hereinafter referred to as the inventor, as being either a sole inventor or one of joint inventors, has invented certain new and useful improvements in

Semiconductor Component Test Device and Method of Testing Semiconductor Components,

for which the inventor has executed an application for United States Patent by his or her signature below, and

WHEREAS **Qualtec Co., Ltd.**, a corporation organized and existing under the laws of Japan, and hereinafter referred to as the assignee, whose mailing address is

230 Sanbōchō 4-Chō, Sakai-ku, Sakai-shi, Osaka-fu, 590-0906, Japan,

is desirous of acquiring the entire rights in the patent application named above, and insofar as the same yields any United States patent(s), the title to and interest in the same:

Now, therefore, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the inventor assigns, and transfers, unto the assignee, the entire rights in the patent application, and the title to and interest in the same insofar as the same yields any United States patent(s); and the inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all any such patent(s) to the assignee, as that of the entire title to and interest in any such patent(s), for the sole use and behoof of the assignee and the assignee's legal representatives, as fully and entirely as any such patent(s) would have been held by the inventor had the present assignment not been made.

Statements Required by 35 U.S.C. § 115(b) and (c)

As the above-named inventor, I hereby declare that:

上記発明者である私は、次のことがらを宣誓します。

The above-identified application was made or authorized to be made by me.

上記の出願は私自身、あるいは私が権限を授与したものによって行われたものです。

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

私は本出願書中にあらわれるもともとの発明者、あるいはもともとの共同発明者です。

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Legal Name of Inventor 発明者の正式氏名		Seiichiro Kihara	Date 日付	2021年11月22日
Signature 署名	未	原誠一郎		

^{*} Declaration for patent application using an Application Data Sheet.

WHEREAS **Hiroshi Takahara**, hereinafter referred to as the inventor, as being either a sole inventor or one of joint inventors, has invented certain new and useful improvements in

Semiconductor Component Test Device and Method of Testing Semiconductor Components,

for which the inventor has executed an application for United States Patent by his or her signature below, and

WHEREAS **Qualtec Co., Ltd.**, a corporation organized and existing under the laws of Japan, and hereinafter referred to as the assignee, whose mailing address is

230 Sanbōchō 4-Chō, Sakai-ku, Sakai-shi, Osaka-fu, 590-0906, Japan,

is desirous of acquiring the entire rights in the patent application named above, and insofar as the same yields any United States patent(s), the title to and interest in the same:

Now, therefore, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the inventor assigns, and transfers, unto the assignee, the entire rights in the patent application, and the title to and interest in the same insofar as the same yields any United States patent(s); and the inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all any such patent(s) to the assignee, as that of the entire title to and interest in any such patent(s), for the sole use and behoof of the assignee and the assignee's legal representatives, as fully and entirely as any such patent(s) would have been held by the inventor had the present assignment not been made.

Statements Required by 35 U.S.C. § 115(b) and (c)

As the above-named inventor, I hereby declare that:

上記発明者である私は、次のことがらを宣誓します。

The above-identified application was made or authorized to be made by me.

上記の出願は私自身、あるいは私が権限を授与したものによって行われたものです。

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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Legal Name of Inventor 発明者の正式氏名		Hiroshi Takahara				Date 日付	2021年11月22日
Signature 署名	喜	净、	势	5			

^{*} Declaration for patent application using an Application Data Sheet.